

2SK2737

Silicon N Channel MOS FET
High Speed Power Switching

HITACHI

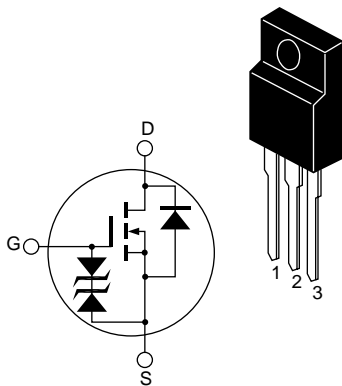
ADE-208-533
1st. Edition

Features

- Low on-resistance
 $R_{DS(on)} = 10 \text{ m}\Omega$ typ.
- Low drive current
- High speed switching

Outline

TO-220CFM



1. Gate
2. Drain
3. Source

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	30	V
Gate to source voltage	V_{GSS}	± 20	V
Drain current	I_D	45	A
Drain peak current	$I_{D(pulse)}^{*1}$	180	A
Body to drain diode reverse drain current	I_{DR}	45	A
Channel dissipation	P_{ch}^{*2}	30	W
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

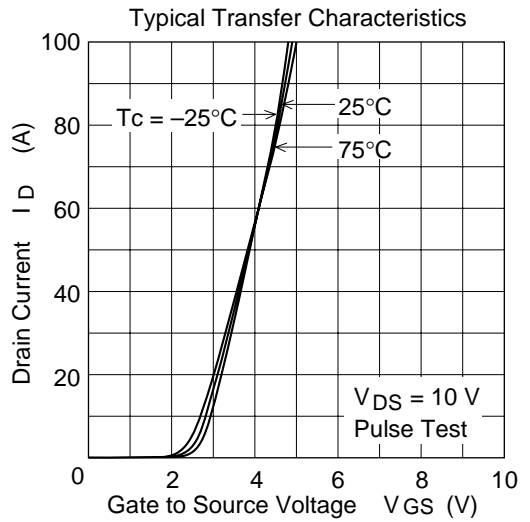
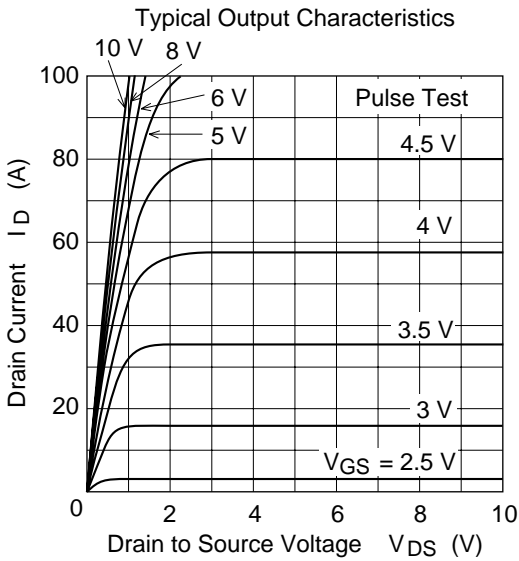
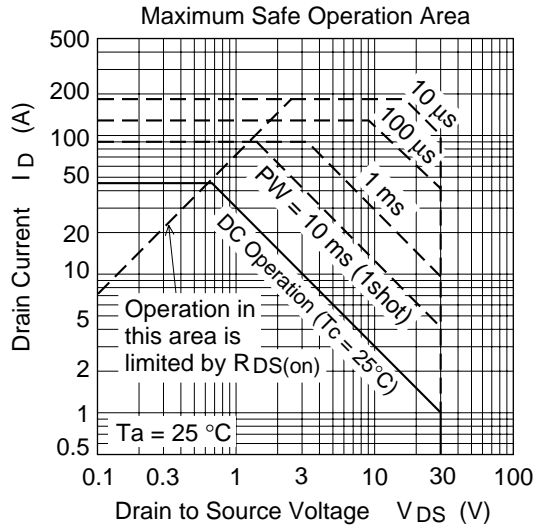
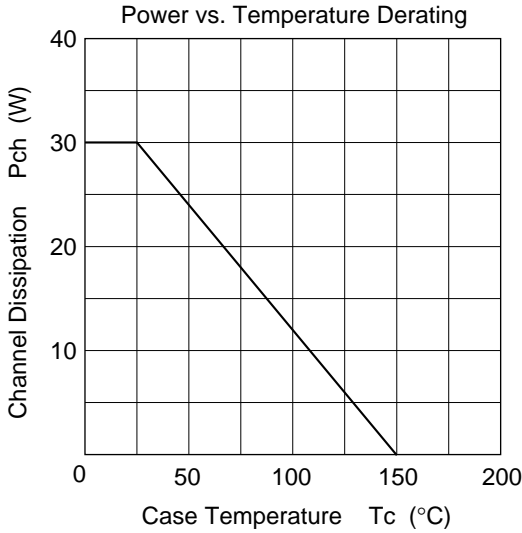
Notes: 1. $PW \leq 10\mu\text{s}$, duty cycle $\leq 1\%$
2. Value at $T_c = 25^\circ\text{C}$

Electrical Characteristics (Ta = 25°C)

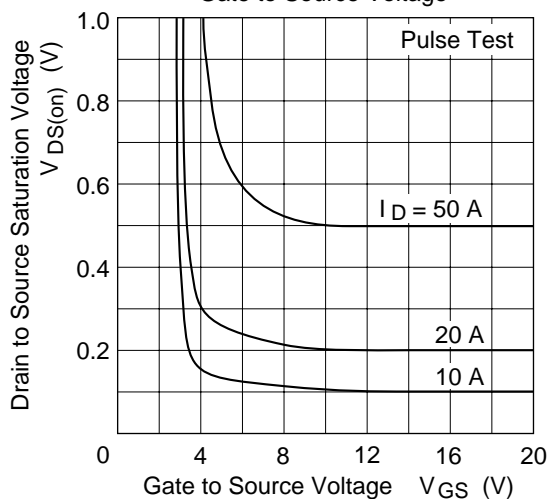
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	30	—	—	V	$I_D = 10\text{mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	—	—	V	$I_G = \pm 100\mu\text{A}, V_{DS} = 0$
Gate to source leak current	I_{GSS}	—	—	±10	μA	$V_{GS} = \pm 16\text{V}, V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	10	μA	$V_{DS} = 30\text{V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	—	2.0	V	$I_D = 1\text{mA}, V_{DS} = 10\text{V}^{*1}$
Static drain to source on state resistance	$R_{DS(on)}$	—	10	14	mΩ	$I_D = 20\text{A}, V_{GS} = 10\text{V}^{*1}$
	$R_{DS(on)}$	—	15	25	mΩ	$I_D = 20\text{A}, V_{GS} = 4\text{V}^{*1}$
Forward transfer admittance	$ y_{fs} $	20	30	—	S	$I_D = 20\text{A}, V_{DS} = 10\text{V}^{*1}$
Input capacitance	C_{iss}	—	1550	—	pF	$V_{DS} = 10\text{V}$
Output capacitance	C_{oss}	—	1050	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	C_{rss}	—	330	—	pF	$f = 1\text{MHz}$
Turn-on delay time	$t_{d(on)}$	—	20	—	ns	$V_{GS} = 10\text{V}, I_D = 20\text{A}$
Rise time	t_r	—	370	—	ns	$R_L = 0.5\Omega$
Turn-off delay time	$t_{d(off)}$	—	170	—	ns	
Fall time	t_f	—	180	—	ns	
Body to drain diode forward voltage	V_{DF}	—	0.95	—	V	$I_D = 45\text{A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t_{rr}	—	75	—	ns	$I_F = 45\text{A}, V_{GS} = 0$ $diF/dt = 50\text{A}/\mu\text{s}$

Note: 1. Pulse test

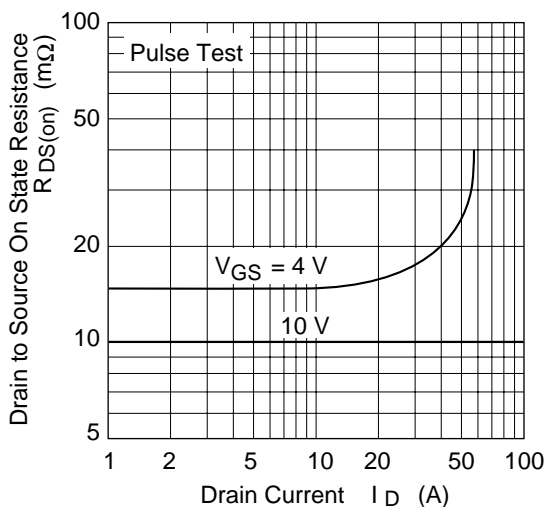
Main Characteristics



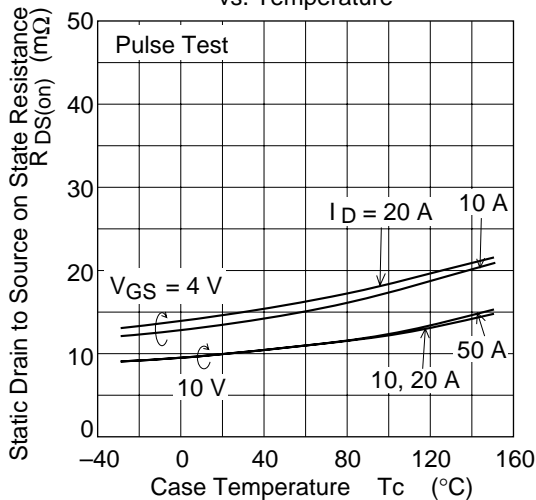
Drain to Source Saturation Voltage vs. Gate to Source Voltage



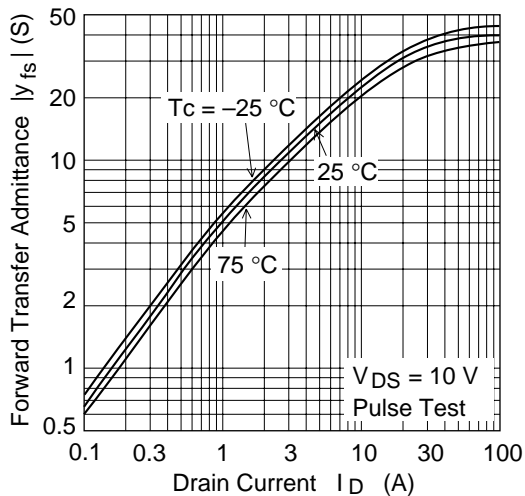
Static Drain to Source on State Resistance vs. Drain Current



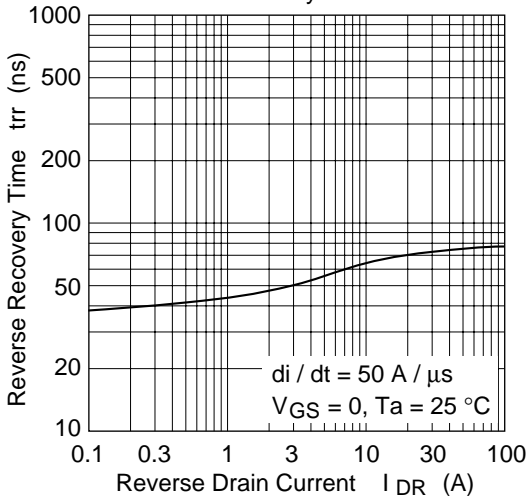
Static Drain to Source on State Resistance vs. Temperature



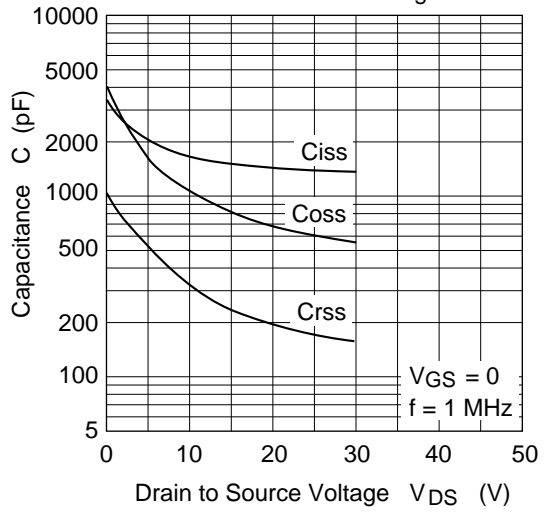
Forward Transfer Admittance vs. Drain Current



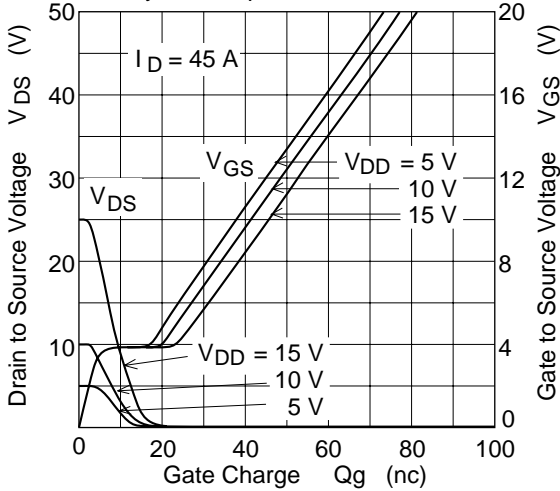
Body to Drain Diode Reverse Recovery Time



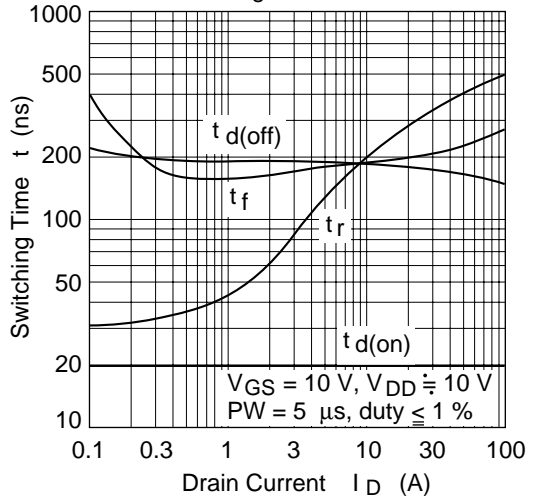
Typical Capacitance vs. Drain to Source Voltage

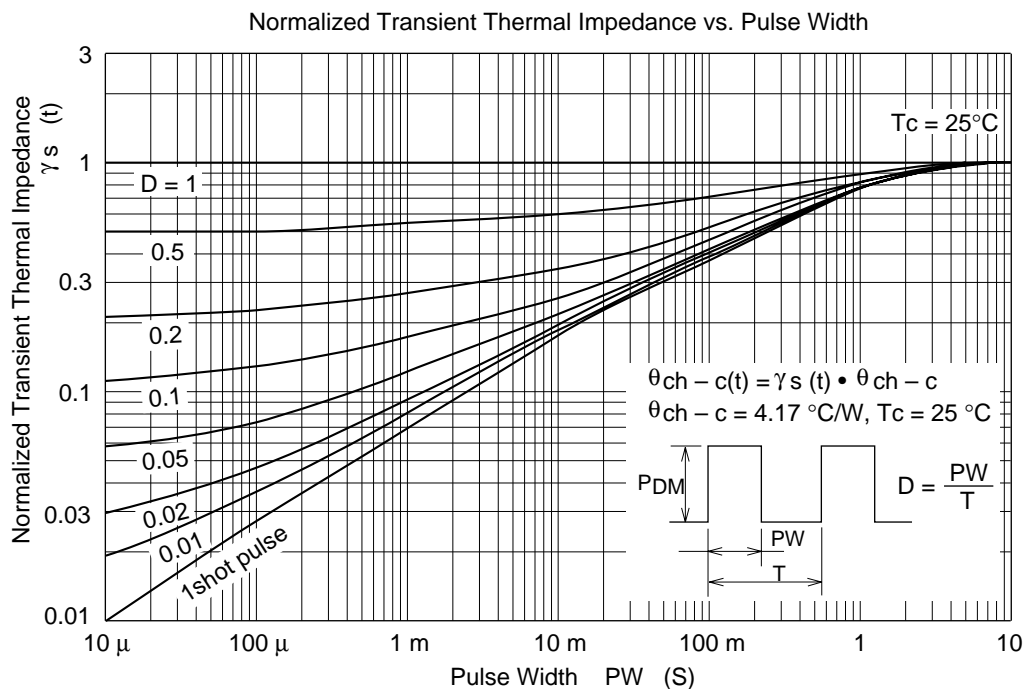
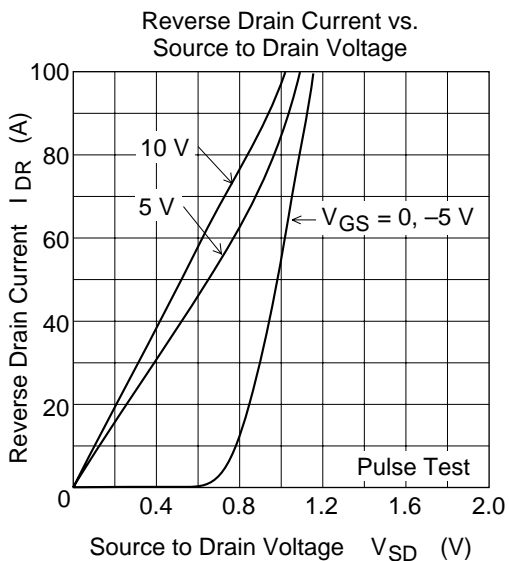


Dynamic Input Characteristics

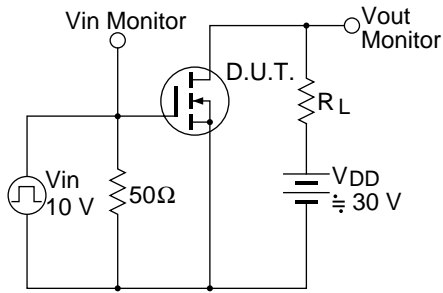


Switching Characteristics

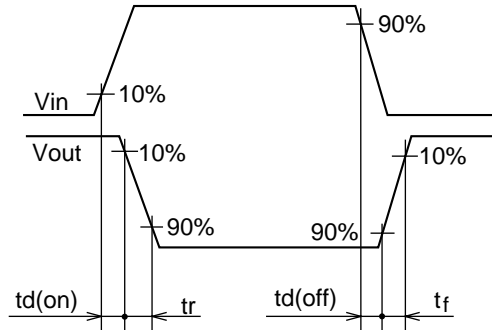




Switching Time Test Circuit

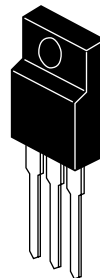
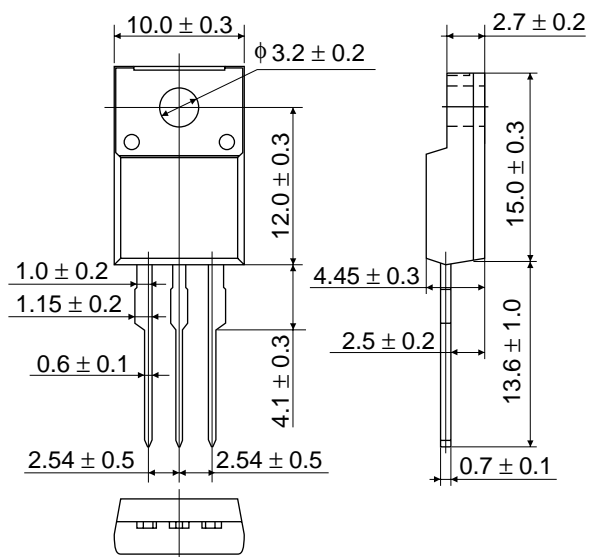


Switching Time Waveforms



Package Dimensions

Unit: mm



Hitachi Code	TO-220CFM
EIAJ	—
JEDEC	—

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HITACHI

Hitachi, Ltd.

Semiconductor & IC Div.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100, Japan
Tel: Tokyo (03) 3270-2111
Fax: (03) 3270-5109

For further information write to:

Hitachi America, Ltd.
Semiconductor & IC Div.
2000 Sierra Point Parkway
Brisbane, CA. 94005-1835
U S A
Tel: 415-589-8300
Fax: 415-583-4207

Hitachi Europe GmbH
Electronic Components Group
Continental Europe
Dornacher Straße 3
D-85622 Feldkirchen
München
Tel: 089-9 91 80-0
Fax: 089-9 29 30 00

Hitachi Europe Ltd.
Electronic Components Div.
Northern Europe Headquarters
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA
United Kingdom
Tel: 0628-585000
Fax: 0628-778322

Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 0104
Tel: 535-2100
Fax: 535-1533

Hitachi Asia (Hong Kong) Ltd.
Unit 706, North Tower,
World Finance Centre,
Harbour City, Canton Road
Tsim Sha Tsui, Kowloon
Hong Kong
Tel: 27359218
Fax: 27306071

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